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978-1-107-40831-9 - Materials, Processes, and Reliability for Advanced Interconnects for Micro- and Nanoelectronics — 2009: Materials Research Society Symposium Proceedings: Volume 1156

Editors: Martin Gall, Alfred Grill, Francesca Iacopi, Junichi Koike and Takamasa Usui

Index

[More information](#)

- Agarwal, Rahul, 149
 Aki, S., 99
 Aksenov, German, 39
 Anthis, J., 73
 Arai, H., 39
 Armini, Silvia, 85

 Bakir, Muhannad, 169
 Baklanov, Mikhail R., 17, 23, 39, 53
 Besser, Paul R., 113
 Beyer, Gerald, 23
 Blonkowski, Serge, 3
 Boag, N., 73
 Braginsky, O.V., 17
 Busawon, Abheesh N., 53

 Calbo, Giovanni, 23
 Chabal, Yves J., 73
 Chen, Fen, 133
 Choi, Samuel, 11
 Ciofi, Ivan, 23

 DeRoest, David, 39
 Dixit, Vijay K., 99, 105
 Dultsev, F.N., 39
 Dziobkowski, Chet, 11

 Eslava, Salvador, 53

 Fang, Nicholas, 141
 Ferreira, Placid, 141
 Fujimoto, Koji, 163

 Gall, Martin, 121
 Gambino, Jeff, 133
 Gudmundsson, Jon T., 59
 Guedj, Cyril, 3

 Hauschildt, Meike, 121
 He, John, 133
 Hernandez, Richard, 121
 Hosaka, S., 99
 Hsieh, Tsung-Eong, 65
 Hsu, Keng, 141

 Huang, Gang, 169

 Iacopi, Francesca, 53
 Ingason, Arni S., 59
 Ito, Kazuhiro, 93
 Itoh, H., 99

 Jacobs, Kyle, 141
 Jordan-Sweet, Jean L., 113

 Kanjolia, R., 73
 Kesters, Els, 45
 Kirschhock, Christine E., 53
 Kitada, Hideki, 163
 Kohama, Kazuyuki, 93
 Koike, Junichi, 99, 105
 Kondoh, Eiichi, 181
 Kovalev, A.S., 17
 Kumar, Anil, 141

 Le, Quoc Toan, 45
 Lee, Tom C., 133
 Lopaev, D.V., 17
 Lux, Marcel, 45

 Maeda, Nobuyuki, 163
 Maekawa, Kazuyoshi, 93
 Maestre Caro, Arantxa, 85
 Maex, Karen, 53
 Magnus, Fridrik, 59
 Majeed, Bivragh, 155
 Malykhin, E.M., 17
 Mankelevich, Y.A., 17
 Marsik, Premysl, 39, 45
 Martens, Johan A., 53
 Matsubara, Masahiro, 181
 Matsumoto, K., 99
 Mongeon, Steve, 133
 Mori, Kenichi, 93
 Mosher, Dave, 133
 Murakami, Masanori, 93
 Murray, Conal E., 113

 Nakamura, Tomoji, 163
 Neishi, Koji, 99, 105

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Index

[More information](#)

- | | |
|--------------------------|-----------------------------|
| Odedra, R., 73 | Soussan, Philippe, 155 |
| Ohba, Takayuki, 163 | Suzuki, Kousuke, 163 |
| Olafsson, Sveinn, 59 | Sylvestre, Alain, 3 |
|
 | |
| Pan, Hung-Chun, 65 | Tai, Leo, 11 |
| Park, Sun Kyung, 73 | Takamure, N., 39 |
| Pawlikowski, Gregory, 31 | Tezcan, Deniz S., 155 |
| Pokrinchak, Phil, 133 | Tökei, Zsolt, 23 |
| Prager, L., 45 | |
| Proshina, O.V., 17 | Urrutia, Jone, 53 |
|
 | |
| Radhakrishnan, Bala, 79 | Van Cauwenberghe, Marc, 155 |
| Rakhimov, A.T., 17 | Vasilieva, A.N., 17 |
| Rakhimova, T.V., 17 | Verdonck, Patrick, 39 |
| Roodenko, K., 73 | Vereecke, Guy, 45 |
| Roy, David, 3 | Verriere, Virginie, 3 |
| Ruythooren, Wouter, 149 | Voloshin, D.G., 17 |
|
 | |
| Sarma, Gorti, 79 | Wielunski, L., 73 |
| Sato, H., 99 | Witt, Christian, 113 |
| Shamiryan, Denis, 39 | |
| Shinosky, Mike, 133 | Zyryanov, S.M., 17 |
| Shirai, Yasuharu, 93 | |

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Index

[More information](#)

- absorption, 39
- additives, 31
- adhesion, 99
- adhesive, 163
- Ag, 141
- amorphous, 65, 105
- atomic layer deposition, 73
- barrier layer, 65, 93, 99
- bonding, 149
- chemical vapor deposition (CVD)
 - (deposition), 39, 99, 105
 - Cu, 11, 85, 105, 113, 121, 133, 149, 163, 181
- defects, 3
- dielectric, 3, 39, 53
 - properties, 17, 23, 31, 133
- diffusion, 17, 65
- electrical properties, 3, 59
- electrodeposition, 85, 163
- electromigration, 121
- electronic material, 59
- H, 23
- infrared (IR) spectroscopy, 45
- kinetics, 121
- lithography (removal), 45
- metalorganic deposition, 181
- microelectro-mechanical (MEMS),
 - 141, 169
- microelectronics, 133, 169
- microstructure, 79
- nano-indentation, 141
- optical properties, 73
- packaging, 149, 155, 169
- photochemical, 45
- plating, 155
- polymer, 31
- porosity, 17
- reactive ion etching, 11, 155
- Ru, 73
- Rutherford backscattering
 - (RBS), 93
- self-assembly, 85
- simulation, 79
- sol-gel, 53
- texture, 79
- thermal stresses, 113
- thin film, 53, 93, 181
- water, 23
- x-ray
 - diffraction (XRD), 59, 113
 - photoelectron spectroscopy (XPS), 11